MOSFET

Metal Oxide Semiconductor Field Effect Transistor

OptiMOS™

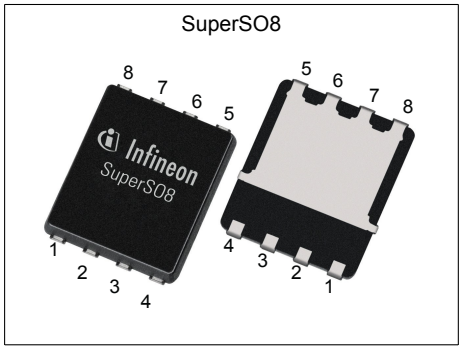
OptiMOS™5 Power-Transistor, 80 V
BSC026N08NS5

Data Sheet

Rev. 2.1
Final

Power Management & Multimarket

1 Description

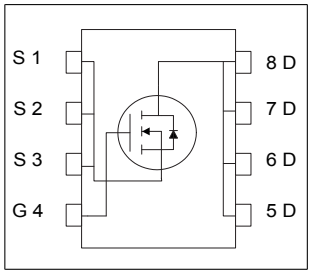


Features

- Optimized for Synchronous Rectification in server and desktop
- 100% avalanche tested
- Superior thermal resistance
- N-channel
- Qualified according to JEDEC[1] for target applications
- Pb-free lead plating; RoHS compliant
- Halogen-free according to IEC61249-2-21

Table 1 Key Performance Parameters

Parameter	Value	Unit
V_{DS}	80	V
$R_{DS(on),max}$	2.6	mΩ
I_D	100	A
Q_{oss}	88	nC
Q_G(0V..10V)	74	nC



Type / Ordering Code	Package	Marking	Related Links
BSC026N08NS5	PG-TDSON-8	026N08NS	-

[1] J-STD20 and JESD22

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2 Maximum ratings

at T_A = 25 °C, unless otherwise specified

Table 2 Maximum ratings

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Continuous drain current	I_D	- - -	- - -	100 100 23	A	V_{GS}=10 V, T_C=25 °C V_{GS}=10 V, T_C=100 °C V_{GS}=10 V, T_A=25 °C, R_{thJA} =50K/W[1)]
Pulsed drain current[2)]	$I_{D,pulse}$	-	-	400	A	T_C=25 °C
Avalanche energy, single pulse[3)]	E_{AS}	-	-	370	mJ	I_D=50 A, R_{GS}=25 Ω
Gate source voltage	V_{GS}	-20	-	20	V	-
Power dissipation	P_{tot}	- -	- -	156 2.5	W	T_C=25 °C T_A=25 °C, R_{thJA}=50 K/W[1)]
Operating and storage temperature	T_j, T_{stg}	-55	-	150	°C	IEC climatic category; DIN IEC 68-1: 55/150/56

3 Thermal characteristics

Table 3 Thermal characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case, bottom	R_{thJC}	-	0.5	0.8	K/W	-
Thermal resistance, junction - case, top	R_{thJC}	-	-	20	K/W	-
Device on PCB, 6 cm² cooling area[1)]	R_{thJA}	-	-	50	K/W	-

[1)] Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm² (one layer, 70 µm thick) copper area for drain connection. PCB is vertical in still air.
[2)] See Diagram 3 for more detailed information
[3)] See Diagram 13 for more detailed information

4 Electrical characteristics

Table 4 Static characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Drain-source breakdown voltage	$V_{(BR)DSS}$	80	-	-	V	V_{GS}=0 V, I_D=1 mA
Gate threshold voltage	$V_{GS(th)}$	2.2	3	3.8	V	V_{DS}=V_{GS}, I_D=115 µA
Zero gate voltage drain current	I_{DSS}	- -	0.1 10	1 100	µA	V_{DS}=80 V, V_{GS}=0 V, T_j=25 °C V_{DS}=80 V, V_{GS}=0 V, T_j=125 °C
Gate-source leakage current	I_{GSS}	-	10	100	nA	V_{GS}=20 V, V_{DS}=0 V
Drain-source on-state resistance	$R_{DS(on)}$	- -	2.2 3.0	2.6 3.9	mΩ	V_{GS}=10 V, I_D=50 A V_{GS}=6 V, I_D=25 A
Gate resistance[1)]	R_G	-	1.9	2.9	Ω	-
Transconductance	g_{fs}	60	120	-	S	|V_{DS}|>2|I_D|$R_{DS(on)max}$, I_D=50 A

Table 5 Dynamic characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input capacitance[1)]	C_{iss}	-	5200	6800	pF	V_{GS}=0 V, V_{DS}=40 V, f=1 MHz
Output capacitance[1)]	C_{oss}	-	840	1100	pF	V_{GS}=0 V, V_{DS}=40 V, f=1 MHz
Reverse transfer capacitance[1)]	C_{rss}	-	38	66	pF	V_{GS}=0 V, V_{DS}=40 V, f=1 MHz
Turn-on delay time	$t_{d(on)}$	-	18	-	ns	V_{DD}=40 V, V_{GS}=10 V, I_D=50 A, $R_{G,ext}$=3 Ω
Rise time	t_r	-	14	-	ns	V_{DD}=40 V, V_{GS}=10 V, I_D=50 A, $R_{G,ext}$=3 Ω
Turn-off delay time	$t_{d(off)}$	-	47	-	ns	V_{DD}=40 V, V_{GS}=10 V, I_D=50 A, $R_{G,ext}$=3 Ω
Fall time	t_f	-	16	-	ns	V_{DD}=40 V, V_{GS}=10 V, I_D=50 A, $R_{G,ext}$=3 Ω

[1)] Defined by design. Not subject to production test.

Table 6 Gate charge characteristics[1)]

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Gate to source charge	Q_{gs}	-	24	-	nC	V_{DD}=40 V, I_D=50 A, V_{GS}=0 to 10 V
Gate charge at threshold	$Q_{g(th)}$	-	14	-	nC	V_{DD}=40 V, I_D=50 A, V_{GS}=0 to 10 V
Gate to drain charge[2)]	Q_{gd}	-	16	23	nC	V_{DD}=40 V, I_D=50 A, V_{GS}=0 to 10 V
Switching charge	Q_{sw}	-	25	-	nC	V_{DD}=40 V, I_D=50 A, V_{GS}=0 to 10 V
Gate charge total[2)]	Q_g	-	74	92	nC	V_{DD}=40 V, I_D=50 A, V_{GS}=0 to 10 V
Gate plateau voltage	$V_{plateau}$	-	4.5	-	V	V_{DD}=40 V, I_D=50 A, V_{GS}=0 to 10 V
Gate charge total, sync. FET	$Q_{g(sync)}$	-	64	-	nC	V_{DS}=0.1 V, V_{GS}=0 to 10 V
Output charge[2)]	Q_{oss}	-	88	117	nC	V_{DD}=40 V, V_{GS}=0 V

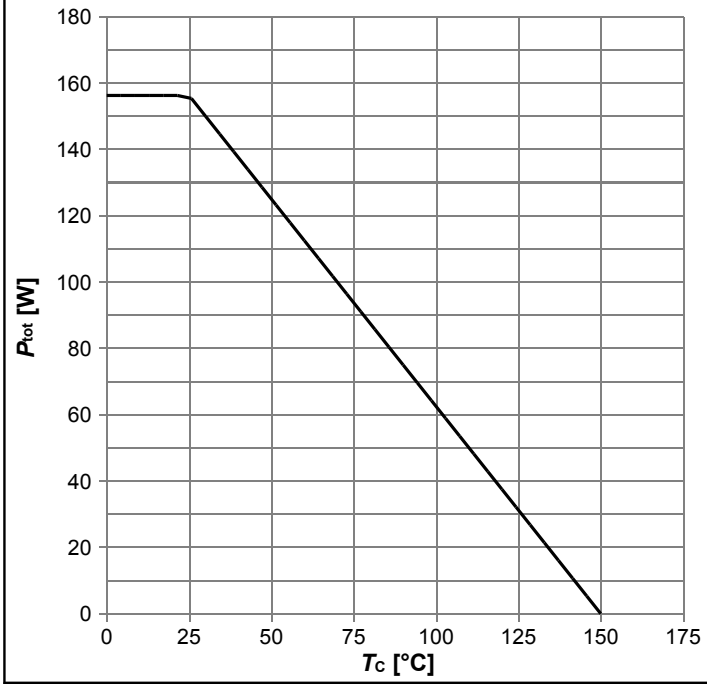
Table 7 Reverse diode

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Diode continuous forward current	I_S	-	-	100	A	T_C=25 °C
Diode pulse current	$I_{S,pulse}$	-	-	400	A	T_C=25 °C
Diode forward voltage	V_{SD}	-	0.85	1.1	V	V_{GS}=0 V, I_F=50 A, T_j=25 °C
Reverse recovery time[2)]	t_{rr}	-	56	112	ns	V_R=40 V, I_F=50A, di_F/dt=100 A/µs
Reverse recovery charge[2)]	Q_{rr}	-	92	184	nC	V_R=40 V, I_F=50A, di_F/dt=100 A/µs

[1)] See ″Gate charge waveforms″ for parameter definition
[2)] Defined by design. Not subject to production test.

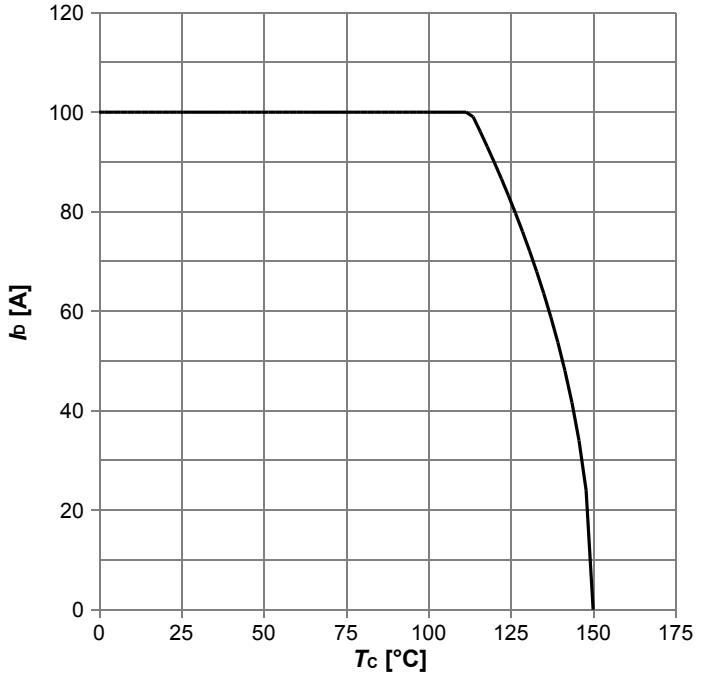
5 Electrical characteristics diagrams

Diagram 1: Power dissipation



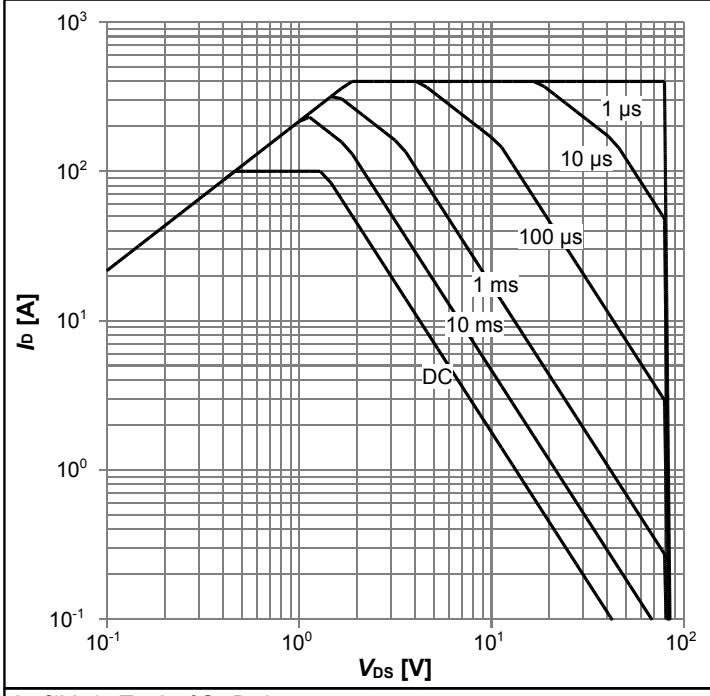
$P_{tot}=f(T_C)$

Diagram 2: Drain current



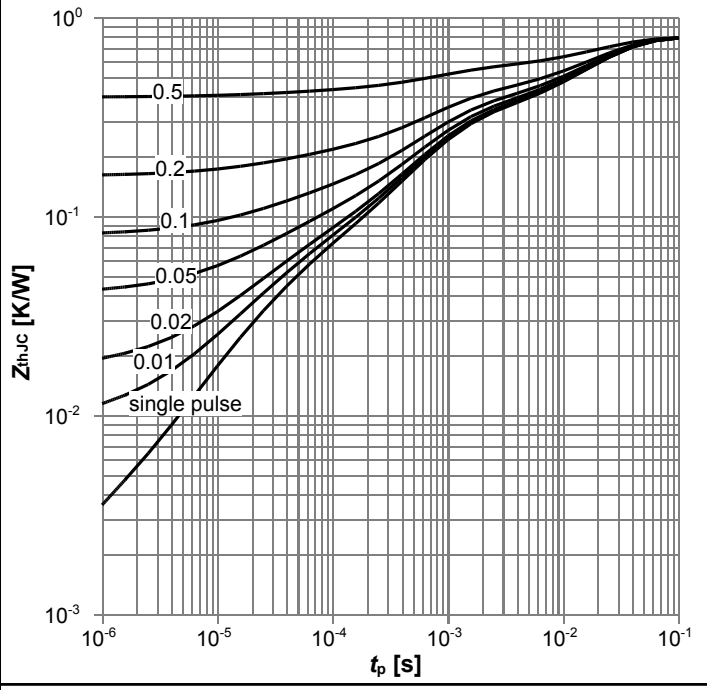
$I_D=f(T_C)$; $V_{GS}\geq 10$ V

Diagram 3: Safe operating area



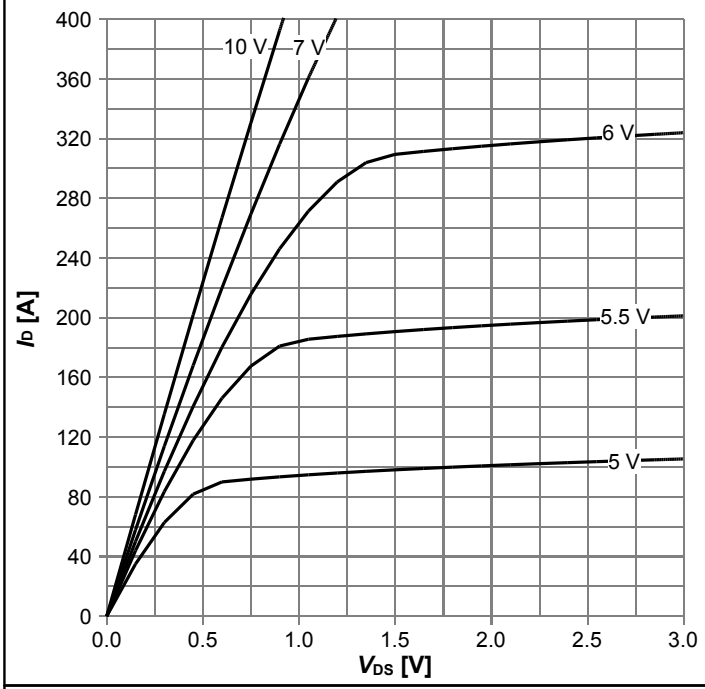
$I_D=f(V_{DS})$; $T_C=25$ °C; $D=0$; parameter: t_p

Diagram 4: Max. transient thermal impedance



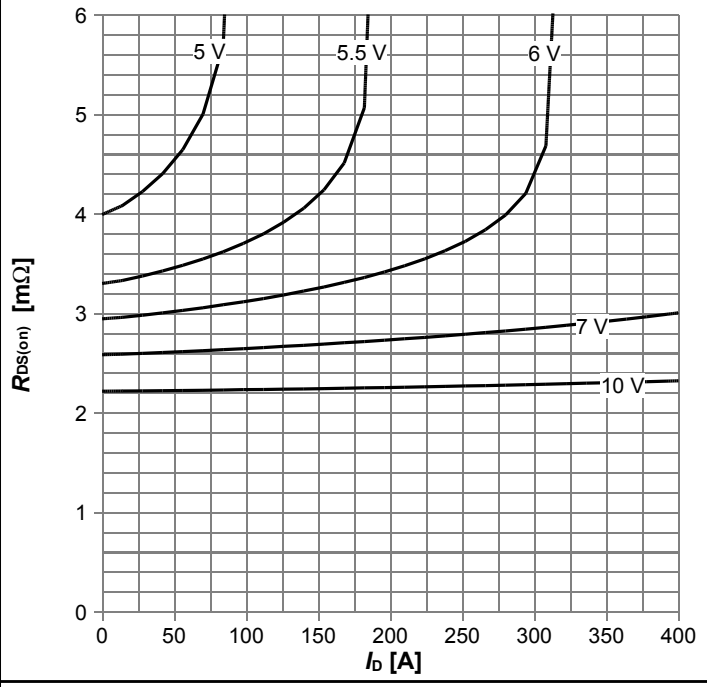
$Z_{thJC}=f(t_p)$; parameter: $D=t_p/T$

Diagram 5: Typ. output characteristics



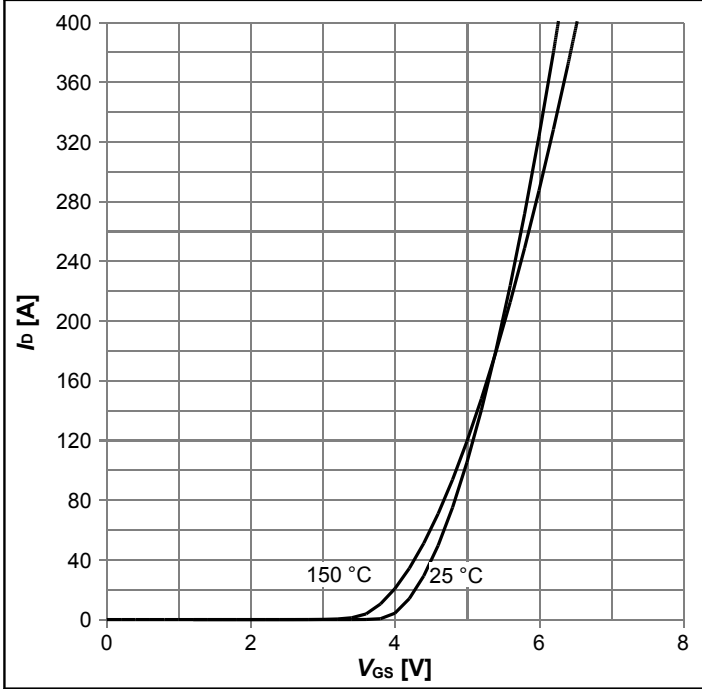
I_D=f(V_{DS}); T_j=25 °C; parameter: V_{GS}

Diagram 6: Typ. drain-source on resistance



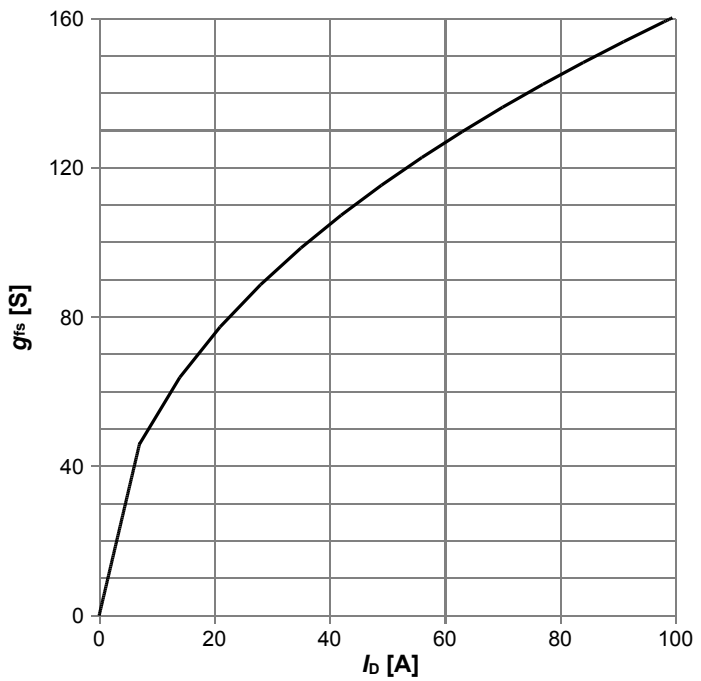
$R_{DS(on)}$=f(I_D); T_j=25 °C; parameter: V_{GS}

Diagram 7: Typ. transfer characteristics



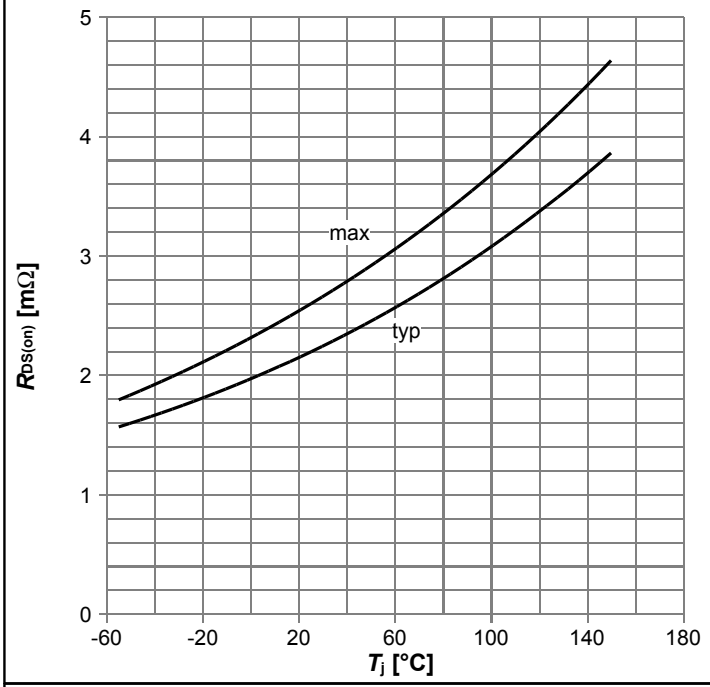
I_D=f(V_{GS}); |V_{DS}|>2|I_D|$R_{DS(on)max}$; parameter: T_j

Diagram 8: Typ. forward transconductance



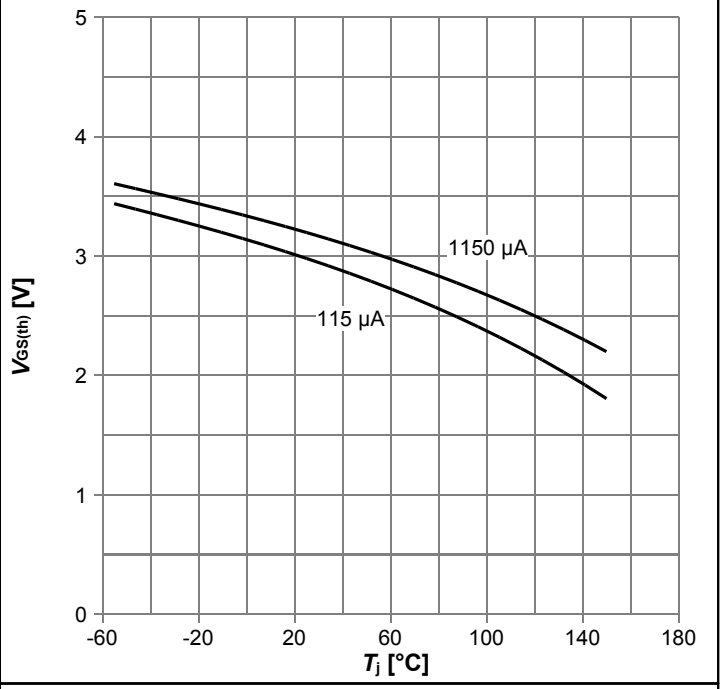
g_{fs}=f(I_D); T_j=25 °C

Diagram 9: Drain-source on-state resistance



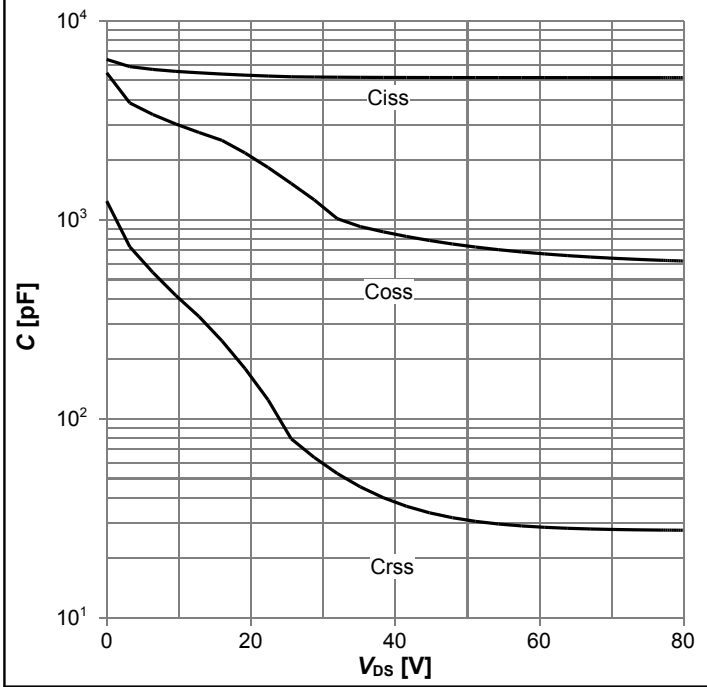
$R_{DS(on)}$=f(T_j); I_D=50 A; V_{GS}=10 V

Diagram 10: Typ. gate threshold voltage



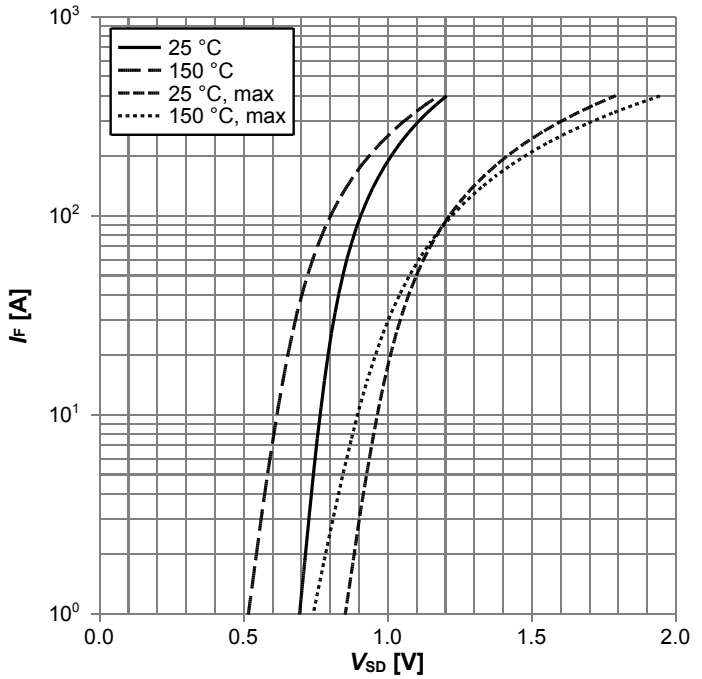
$V_{GS(th)}$=f(T_j); V_{GS}=V_{DS}

Diagram 11: Typ. capacitances



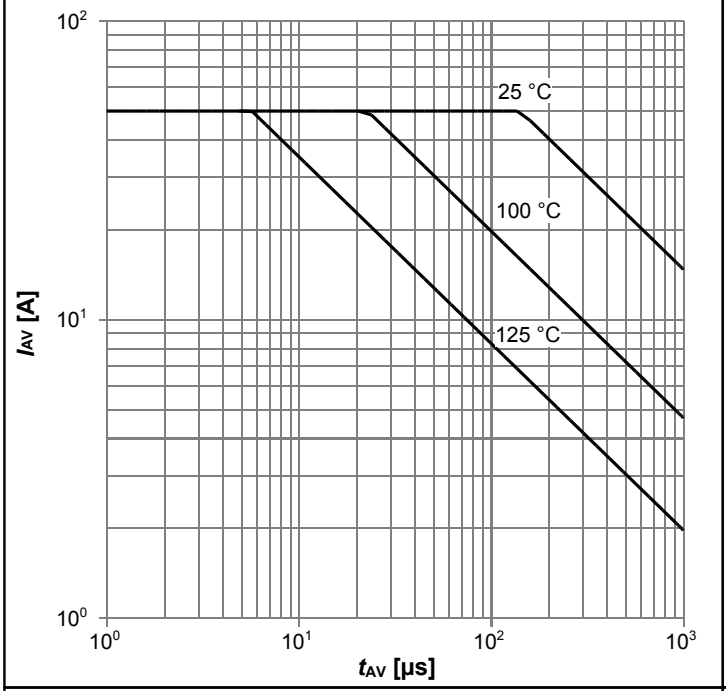
C=f(V_{DS}); V_{GS}=0 V; f=1 MHz

Diagram 12: Forward characteristics of reverse diode



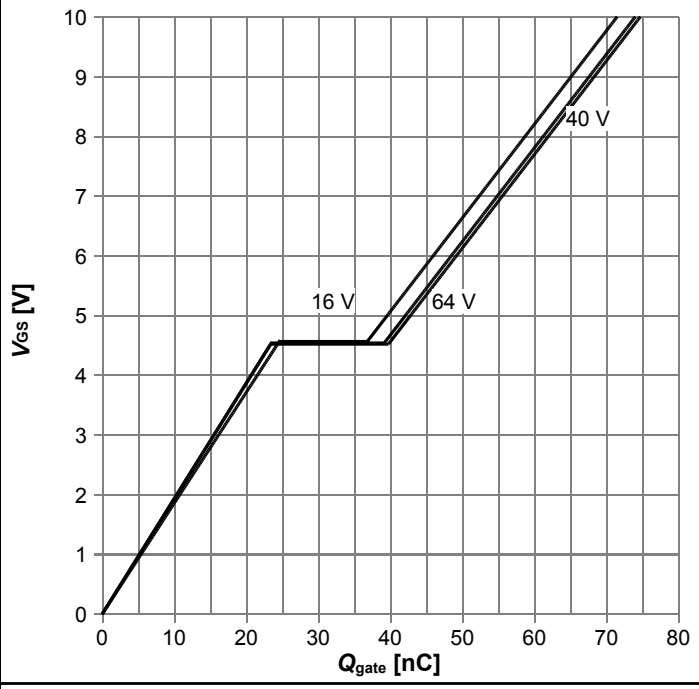
I_F=f(V_{SD}); parameter: T_j

Diagram 13: Avalanche characteristics



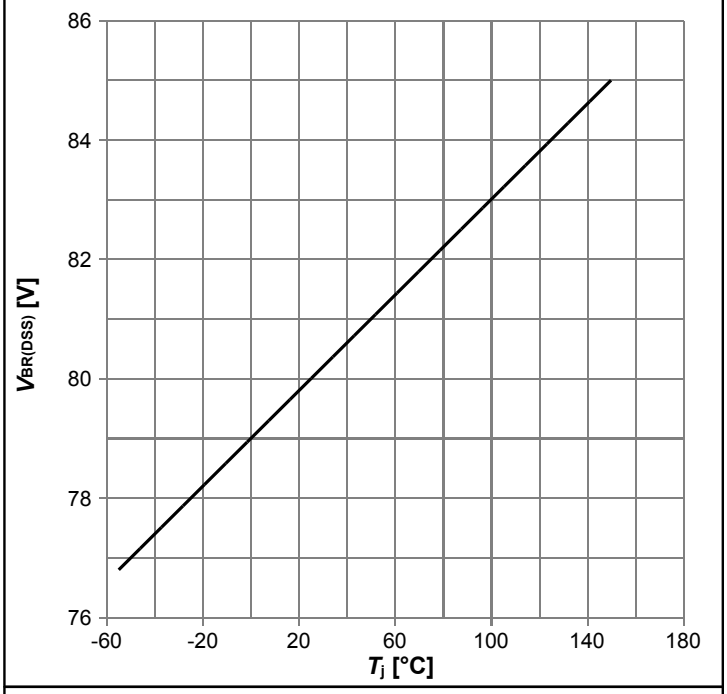
$I_{AS}=f(t_{AV})$; $R_{GS}=25\ \Omega$; parameter: $T_{j(start)}$

Diagram 14: Typ. gate charge



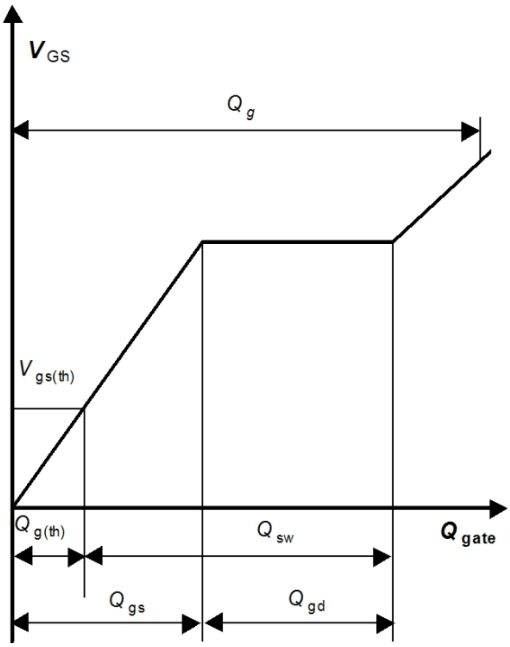
$V_{GS}=f(Q_{gate})$; $I_D=50$ A pulsed; parameter: V_{DD}

Diagram 15: Drain-source breakdown voltage

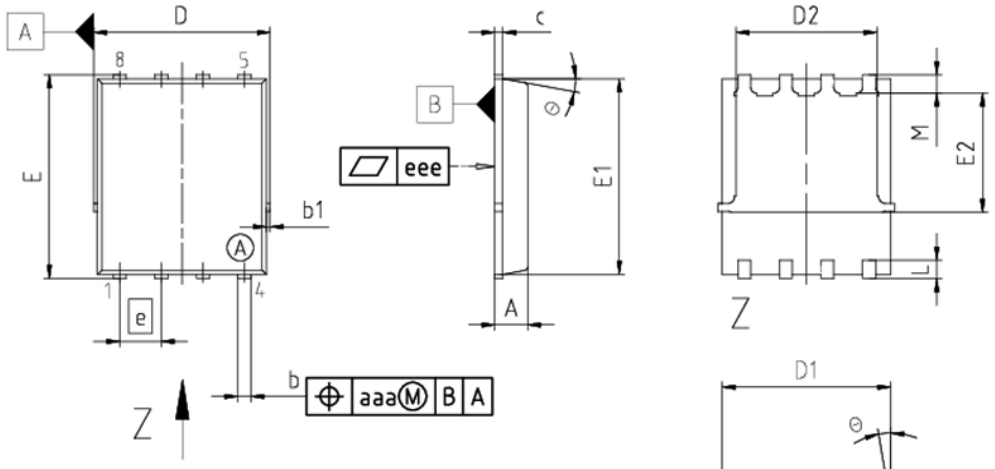


$V_{BR(DSS)}=f(T_j)$; $I_D=1$ mA

Gate charge waveforms



6 Package Outlines



DIM	MILLIMETERS	
	MIN	MAX
A	0.90	1.10
b	0.31	0.54
b1	0.02	0.22
c	0.15	0.35
D	5.15	5.49
D1	4.95	5.35
D2	3.70	4.40
E	5.95	6.35
E1	5.70	6.10
E2	3.40	3.80
e	1.27	
N	8	
L	0.45	0.71
M	0.45	0.75
Θ	8.5°	12°
aaa	0.25	
eee	0.08	

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SCALE 0 2 0 2 4mm
EUROPEAN PROJECTION
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REVISION 04

Figure 1 Outline PG-TDSON-8, dimensions in mm

Revision History

BSC026N08NS5

Revision: 2015-08-31, Rev. 2.1

Previous Revision		
Revision	Date	Subjects (major changes since last revision)
2.0	2014-12-18	Release of final version
2.1	2015-08-31	Rev. 2.0

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